

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
ZHONGXI HUANG	01/18/2017
JIANKUN ZHOU	01/18/2017
JINLONG LI	01/18/2017
GUOPING ZHANG	01/18/2017
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<b>Name:</b>	TYCO ELECTRONICS AMP SHANGHAI LTD.
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<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15411446
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<b>NAME OF SUBMITTER:</b>	SALVATORE ANASTASI
<b>SIGNATURE:</b>	/Salvatore Anastasi/
<b>DATE SIGNED:</b>	01/24/2017
<b>Total Attachments: 1</b> source=Assignment#page1.tif	

**COMBINED DECLARATION AND ASSIGNMENT**

As a below-named inventor, I hereby declare that:

this declaration is directed to inventions and improvements disclosed in:

- the attached application, or
- United States application or PCT international application number \_\_\_\_\_  
 filed on \_\_\_\_\_, entitled Electrophoretic Coating and Preparation Method Thereof, Electrophoretic Coating Process and Selective Plating Process ("the APPLICATION")

The APPLICATION was made or authorized to be made by me;

I believe that I am the original inventor or an original joint inventor of a claimed invention in the APPLICATION;

I have reviewed and understand the contents of the APPLICATION, including the claims, and I am aware of the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37.C.F.R. 1.56; AND

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

As a below named and signing inventor, acknowledging that I have assigned or have obligations to assign the APPLICATION to:

Tyco Electronics (Shanghai) Co. Ltd., and Tyco Electronics AMP Shanghai Ltd. ("ASSIGNEE"), corporations organized and existing under and by virtue of the laws of *China* having its principal place of business at Sections F and G Level I Building 15 No. 999 Yinglum Road China (Shanghai) Pilot Free Trade Zone Shanghai China AND No. 668 Guiping Road, Caohejing Hi-tech Zone, Shanghai, China,

for a valuable consideration, the receipt of which is hereby acknowledged, I do hereby sell, assign, transfer and set over unto the said ASSIGNEE, its successors and assigns, my full and entire right, title and interest in and to the APPLICATION, the inventions and improvements disclosed in the APPLICATION, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent to be granted and issued therefor, not only for, to and in the rights under the International Convention, and all reissues, re-examinations, renewals or extensions thereof, and I hereby authorize and request the United States Patent and Trademark Office and/or other patent office(s) to issue said Letters Patent to said ASSIGNEE, its successors and assigns, in accordance with this assignment

Legal Name	Signature	Date
HUANG, Zhongxi	Huang, Zhongxi	2017. 01. 18
ZHOU, Jiankun	Zhou, Jiankun	2017. 01. 18
LI, Jinlong	Li Jinlong	2017. 1. 18
ZHANG, Guoping	Zhang Guoping	2017. 1. 18